



(1.00 mm) .0394"

POLARIZED MICRO HEADER & SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BKT or www.samtec.com?BKS

Insulator Material:
Liquid Crystal Polymer
Terminal Material:
Phosphor Bronze
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Current Rating:
2.8 A per pin
(2 pins powered)
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(1.40 mm) .055" minimum
Normal Force:
40 grams (0.39 N) average
Max Cycles:

PROCESSING

100 with 10 μ" (0.25 μm) Au

RoHS Compliant:

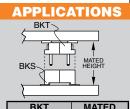
Lead-Free Solderable: Yes SMT Lead Coplanarity: (0.10 mm) .004" max

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



NO. OF **BODY PLATING** BKT **OPTIONS POSITIONS STYLE OPTION** Mates with: Specify -S BODY = Shrouded **STYLE** (15 positions 07 thru 69 = Gold flash on post, minimum) from (Odd lead counts only) Matte Tin on tail chart = Alignment - - - + : 10 μ" (0.25 μm) Gold on post Pin BOARD (2.54) (5.59) .100 .220 **BODY** Matte Tin on tail (Metal or SPACE (Mated with BKS) STYLE plastic at 0 0 + #000# Samtec (1.93)(3.91)-01 (4.14).163discretion) .076 .154 (13 positions **←** (0.50) .020 TYP (2.29)(4.27) -02 (4.50).177minimum) .090 .168 -(0.31) .012 SQ TYP (2.79)(4.78)(1.65) -03(5.00).197(6.35) −P .110 .188 = Pick & (5.77) (3.78)_ _ _ _ -04 (6.00).236Place Pad _____A .149 (13 positions (4.80)(6.78)(0.50) .0197 x ← (No. of positions +1) → + (0.25) .010 -05 (7.00).276(0.50) .0197 x minimum) (No. of positions +1) + (2.44) .096 (4.17 x 5.71) .164 x .225 -TR -S OPTION = Tape & Reel Packaging (0.20) (3.61) В (0.89) -.035 DIA -P OPTION -A OPTION

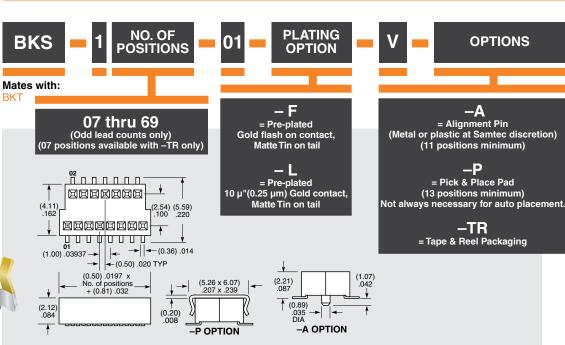


BKT	MATED
LEAD STYLE	HEIGHT*
-01	(4.14) .163
-02	(4.50) .177
-03	(5.00) .197
-04	(6.00) .236
-05	(7.00) .276
*Processing conditions will affect mated height.	



Note:

Some sizes, styles and options are non-standard, non-returnable.



Due to technical progress, all designs, specifications and components are subject to change without notice.

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